Amendments to the Specification:

In the Title:

Please replace the title with the following rewritten title:

-- SEMICONDUCTOR WAFER PROTECTION STRUCTURE AND LAMINATED PROTECTIVE SHEET FOR USE THEREIN --

Please replace the paragraph beginning at page 3, line 4, with the following rewritten paragraph:

-- JP-A-2000-353682 and JP-A-2002-57208 (now JP-A-2003-129011 and JP-A-2003-261842 respectively) disclose techniques wherein a protective sheet is applied to a semiconductor wafer and is cut into a slightly smaller size than the maximum wafer diameter, and the wafer is subjected to subsequent steps such as backgrinding. These techniques can suppress "play" of the protective sheet, so that the vibration of the protective sheet during backgrinding can be reduced. However, they cannot prevent contact of the wafer edges to the sidewalls of the wafer cassette during transportation. Meanwhile, the wafer backgrinding is often followed by application of an adhesive sheet to the ground wafer surface for various purposes such as formation of a die-bonding adhesive layer. After the adhesive sheet is applied, the protective sheet is ~~peeld~~ peeled to transfer the wafer to the adhesive sheet. Herein, the adhesive sheet applied to the wafer is cut in substantially the same diameter as the wafer. The cutting of the adhesive sheet is performed by running a cutter along the outer periphery of the wafer. Accordingly, the adhesive sheet can be cut in substantially the same diameter as the wafer. However, the cutting blade is brought into contact with the outer periphery of the wafer and often damages the wafer. --

Please replace the paragraph beginning at page 12, line 20, with the following rewritten paragraph:

-- Of the above rigid films, preferred are those that do not cause adverse ~~affects~~ effects such as ionic contamination on the wafer. Specifically, polyethyleneterephthalate films, polypropylene films, polyethylenenaphthalate films and polyamide films are particularly preferred. --

Please replace the paragraph beginning at page 13, line 14, with the following rewritten paragraph:

-- The energy radiation-curable ~~Pressure-sensitive~~ pressure-sensitive adhesives generally contain an acrylic PSA and an energy radiation-curable compound as main components. --

Please replace the paragraph beginning at page 13, line 17, with the following rewritten paragraph:

-- For example, low-molecular weight compounds having in the molecule at least two photopolymerizable carbon-carbon double bonds that can be converted into a three-dimensional network structure by light irradiation as disclosed in JP-A-S60-196956 and JP-A-S60-223139 are widely used as the energy radiation-curable compounds incorporated in the energy radiation-curable ~~Pressure-sensitive~~ pressure-sensitive adhesives. Specific examples thereof include trimethylolpropane triacrylate, pentaerythritol triacrylate, pentaerythritol tetraacrylate, dipentaerythritol monohydroxypentaacrylate, dipentaerythritol hexaacrylate, 1,4-butylene glycol diacrylate, 1,6-hexanediol diacrylate, polyethylene glycol diacrylate, and oligomers such as oligoester acrylates and urethane acrylates. --

Please replace the paragraph beginning at page 17, line 7, with the following rewritten paragraph:

-- The adhesives for firmly bonding the first and the second protective layers 1 and 2 include rubber-based and acryl-based permanent-bonding ~~Pressure-sensitive~~ pressure-sensitive adhesives and polyester-based and polyamide-based dry laminating adhesives. The adhesives for separably laminating the first and the second protective layers 1 and 2 include the above-mentioned ~~Pressure-sensitive~~ pressure-sensitive adhesives for the PSA layer 3. The thickness of the adhesive layer 4 may vary depending on the material, and is generally in the range of about 1 to 100 μm, and preferably about 3 to 50 μm. --

Please replace the paragraph beginning at page 31, line 13, with the following rewritten paragraph:

-- 50 ~~Parts~~ parts by weight ~~of an urethane~~ of a urethane acrylate oligomer having a weight-average molecular weight of 5000 (manufactured by ARAKAWA CHEMICAL INDUSTRIES, LTD.), 25 parts by weight of isobornyl acrylate, 25 parts by weight of phenylhydroxypropyl acrylate, 2.0 parts by weight of a photopolymerization initiator (IRGACURE 184 manufactured by CIBA SPECIALTY CHEMICALS) and 0.2 part by weight of phthalocyanine pigment were mixed together to give a photocurable resin composition as a material for forming a stress relaxation film. --

Please replace the paragraph beginning at page 32, line 13, with the following rewritten paragraph:

-- An energy radiation-curable copolymer having an energy radiation polymerizable group at a side chain was compounded with 5 parts by weight of a curing agent (addition product of ~~toluylene~~ tolylene diisocyanate and trimethylolpropane) and 5 parts by ~~weight a~~ weight of a photopolymerization initiator (IRGACURE 184 manufactured by CIBA SPECIALTY CHEMICALS) to prepare a PSA. The above energy radiation-curable copolymer had been obtained by reaction of 100 parts by weight of a copolymer that consisted of 85 parts by weight of n-butyl acrylate and 15 parts by weight of 2-hydroxyethyl acrylate and had a weight-average molecular weight of about 650000, with 16 parts by weight of methacryloyloxyethyl isocyanate. The thus-obtained PSA was applied to a PET release film (SP-PET 3801 manufactured by LINTEC CORPORATION, thickness: 38 μm) with use of a roll knife coater so as to achieve a dry thickness of 15 μm, followed by drying. The resultant adhesive layer was transferred to the stress relaxation film prepared in (1). Thus, a first protective layer 1 was prepared. --